



VMDSEMI

**VUSP010R14ANA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	140mΩ@10V	3A
	150mΩ@4.5V	

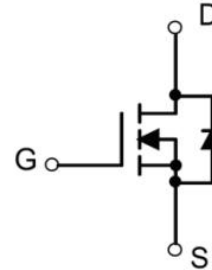


Figure 1 Symbol of VUSP010R14ANA

## Features

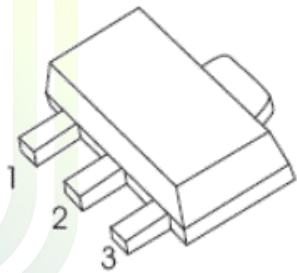
- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

## Application

- Power Switching Application

## Package Type

1. GATE
2. DRAI
3. SOURCE



## SOT-89

Figure 2 Package Type of VUSP010R14ANA

## Ordering Information

Product Name	Package
VUSP010R14ANA	SOT-89

**Absolute Maximum Ratings** ( $T_A=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	$T_C=25\text{ }^\circ\text{C}$	A
Continuous Drain Current <sup>Note1</sup>		$T_A=25\text{ }^\circ\text{C}$	
Pulsed Drain Current <sup>Note2</sup>			
Total Power Dissipation <sup>Note4</sup>	$P_D$	$T_C=25\text{ }^\circ\text{C}$	W
Total Power Dissipation <sup>Note4</sup>		$T_A=25\text{ }^\circ\text{C}$	
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

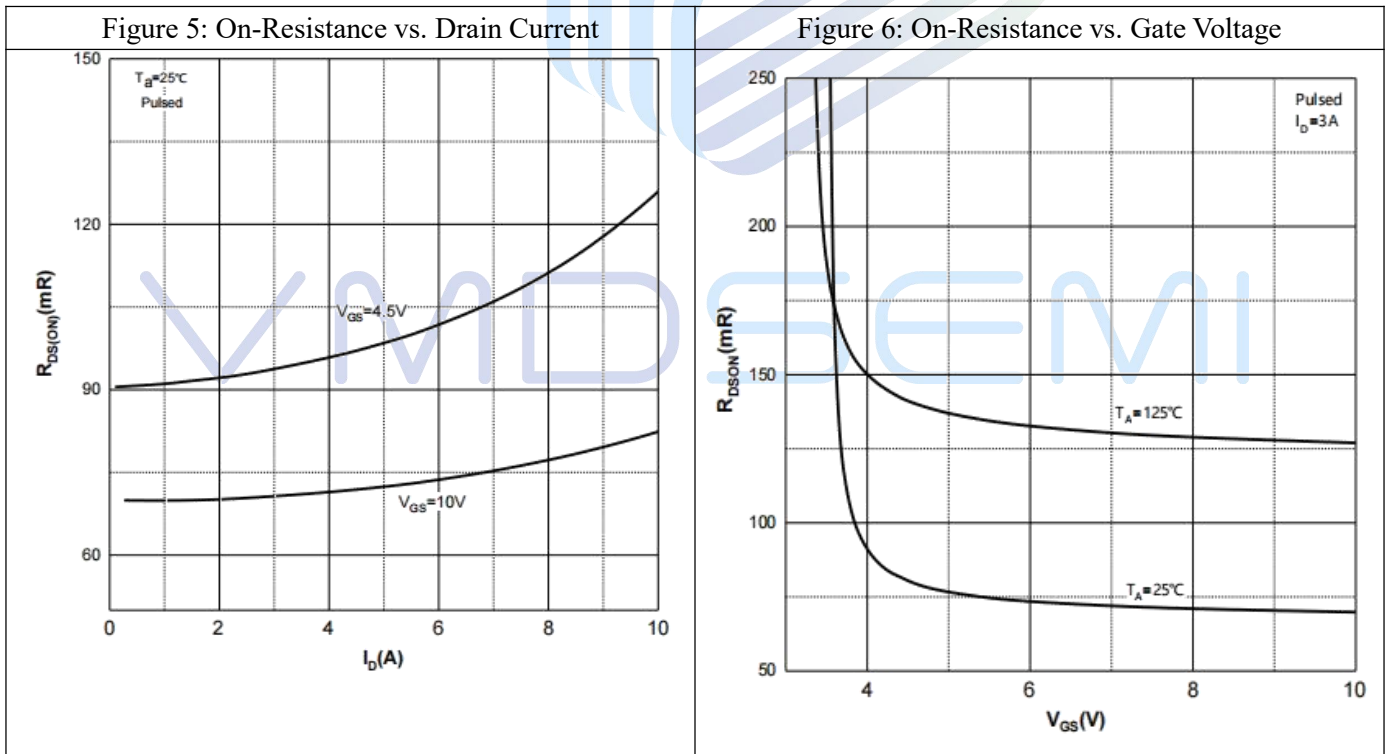
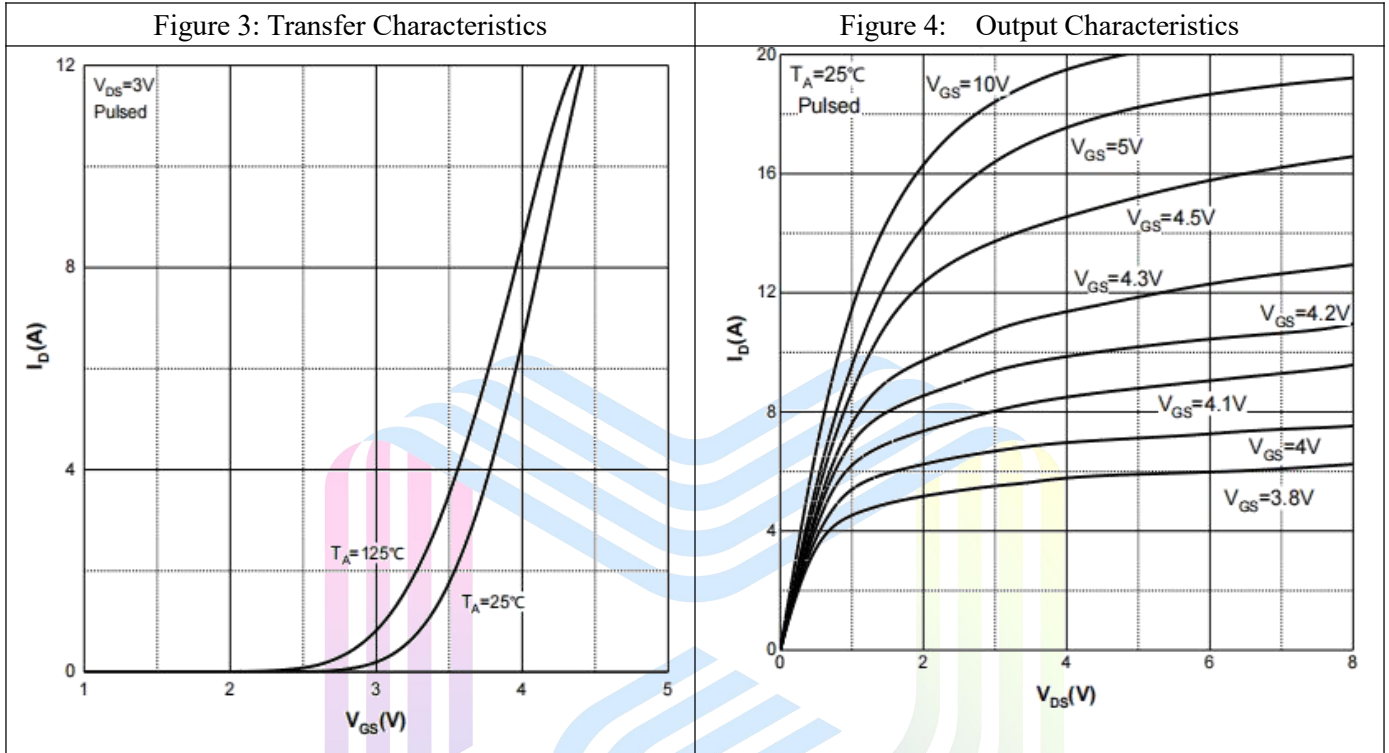
Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note5</sup>	$R_{\theta JA}$		80		$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		45		$^\circ\text{C/W}$

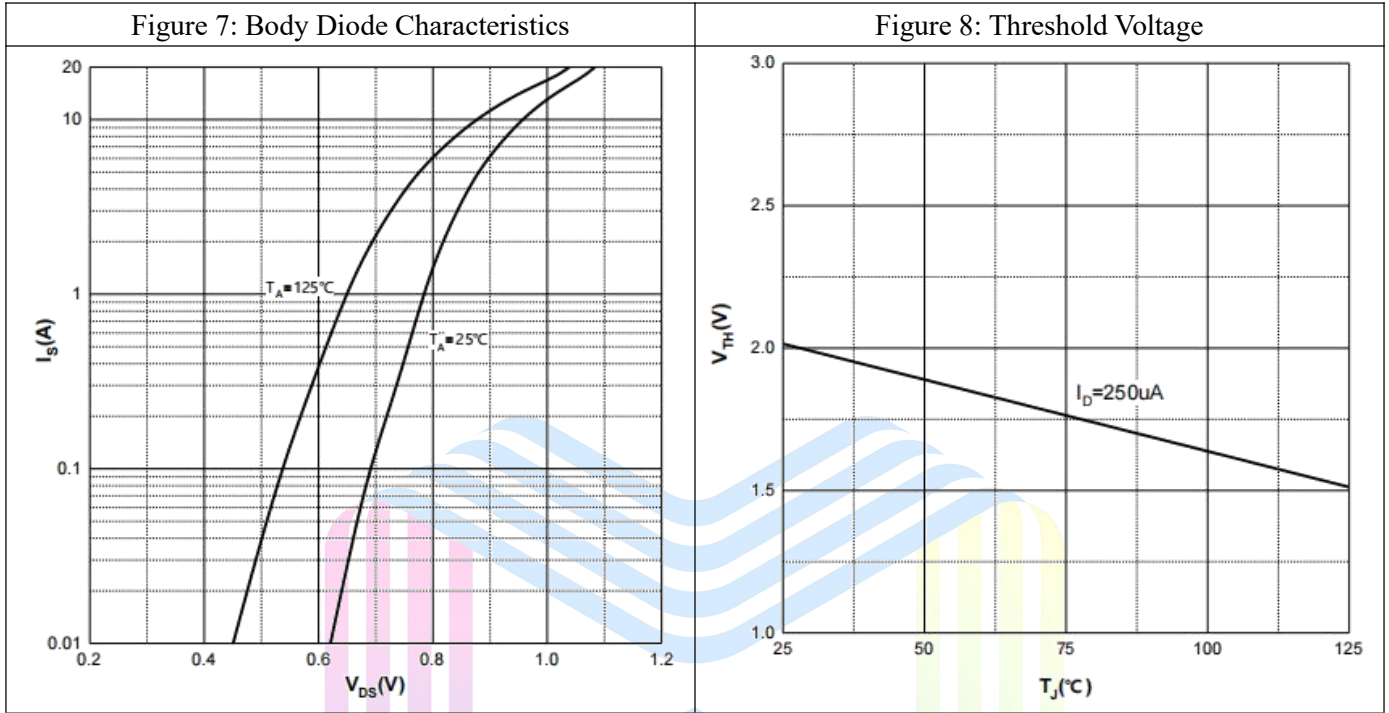
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	2	3	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=3A$		68	140	mΩ
		$V_{GS}=4.5V, I_D=3A$		84	150	
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=10V, I_D=3A$	3			S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V$		790		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		31		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		28		pF
Total Gate Charge	$Q_g$	$V_{DS}=50V$		18		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		3		
Gate-Drain Charge	$Q_{gd}$	$I_D=3A$		3.6		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.3		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		17		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		7		
Turn-off Delay Time	$t_{d(off)}$	$R_L=17\Omega$		35		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		6		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=3A$			1.2	V

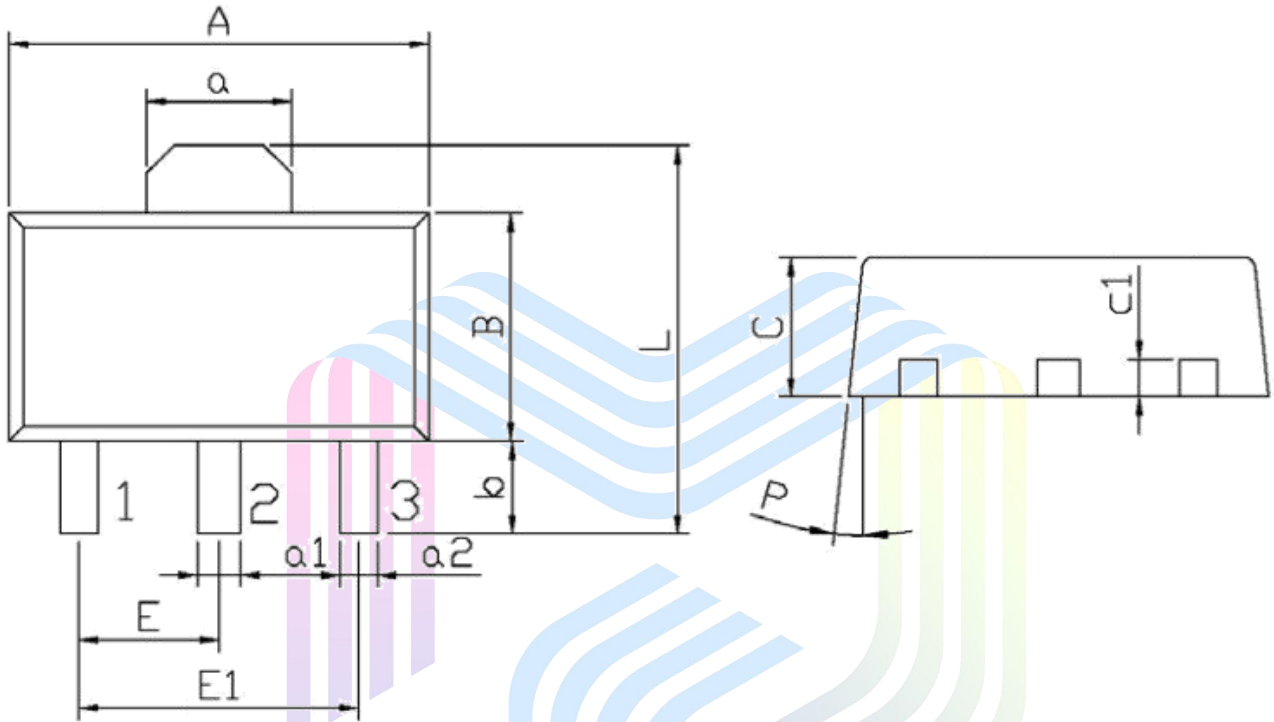
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 5.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

**Typical Performance Characteristics**




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**Mechanical Dimensions:**
**SOT-89 Package Information**


Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.4	4.7	a1	0.36	0.56
B	2.35	2.65	a2	0.30	0.50
L	3.878	4.478	C	1.40	1.70
a	1.45	1.65	c1	0.35	0.50
E	1.40	1.60	P	6°	
E1	2.80	3.20			
b	0.80	1.20			

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